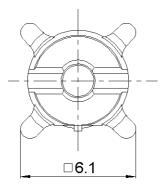
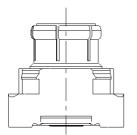
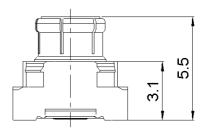
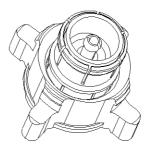
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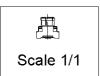
Series: MMBX











All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	BRONZE,BRASS BERYLLIUM COPPER; BRASS - PTFE	NPGR NPGR
:	-	-

**Issue:** 0808 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



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Series: MMBX

**PACKAGING** 

## **SPECIFICATION**

Standard	Unit	Other
100	'W' option	Contact us

### **ELECTRICAL CHARACTERISTICS**

## **ENVIRONMENTAL**

Impedance  $50 \Omega$ 

Frequency 0-12.4 GHz

VSWR 1.065 + 0,0000 x F(GHz) Maxi

Insertion loss  $0.12 \ \sqrt{F(GHz)} \ dB \ Maxi$  RF leakage - (  $100 \ - F(GHz)) \ dB \ Maxi$ 

Voltage rating 330 Veff Maxi Dielectric withstanding voltage Insulation resistance 1000 Veff mini 1000 M $\Omega$  mini

Operating temperature -55/+155 ° C Hermetic seal NA Atm.cm3/s

Panel leakage NA

## **OTHER CHARACTERISTICS**

Assembly instruction

Others:

to 2GHz (1.106 --- 2 to 6GHz) Interface MMBX only ,up to 2.5GHz PCB to PCB -45 dB up to 2.5 GHz

## **MECHANICAL CHARACTERISTICS**

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

10 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

Weight **0,4200** g

**Issue:** 0808 B

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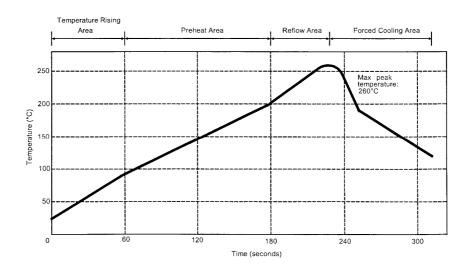
# SOLDER PROCEDURE OF MMBX RECEPTACLE IN INDUSTRIAL ENVIRONMENT

- 1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application.

  We recommend a low residue flux.

  We advise a thickness of 150 priors page (5.850 priors inch.) Verify that the address of the game.
  - We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
   A video camera is recommended for positioning of the component.
   Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven. Below please find, the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged.
- 5. Verification of solder joints and position of the component by visual inspection.

## **TEMPERATURE PROFILE**



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

**Issue:** 0808 B

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necessary.

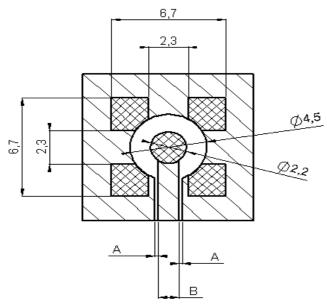


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Series : MMBX

## MMBX SERIES INFORMATIONS

## **PCB**



### **COPLANAR LINE**

Pattern and signal are on the same side The material of PCB is epoxy resin (FR4). (Er = 4.6)

The solder resist should be printed Except for the land pattern on the PCB



## **Pattern**



## APPLICATION $75\Omega$

#### WITH B = 0.55mm

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,350
1,0	0,360
1,2	0,365
1,6	0,375

#### APPLICATION 50Ω

### WITH B = 1,2mm

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,190
1,0	0,200
1,2	0,205
1.6	0.210

**Issue:** 0808 B

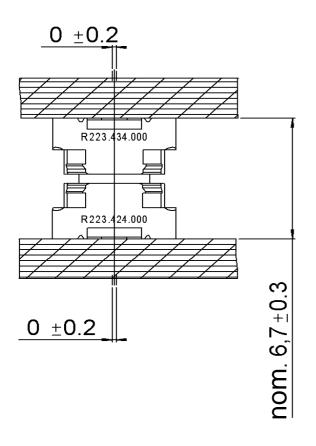
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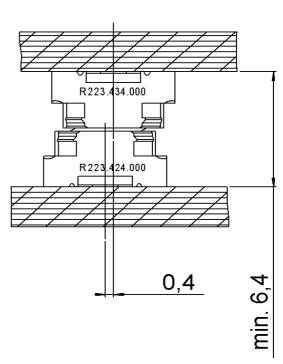
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Series: MMBX

## **MMBX SERIES INFORMATIONS**





**Issue:** 0808 B

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